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# PROCEEDINGS

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# Micro Materials

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## Contents

Opening Addresses	61
Plenary Lectures	71
Packaging Materials	215
Nanomaterials	315
Micro- and NanoProbe Techniques	327
High Temperature Electronics and Thermal Problems	349
Thin Films and Layers	375
Indentation Methods, Layers, Interfaces	391
Sensor- and Actuator Materials	417
Solder Materials, Bonding, Joining	429
Stress, Strain, Reliability	463
Mechanical Properties and Reliability	487
Damage and Failure Mechanisms, Crack, Fracture, Fatigue	541
Optical Methods	587
Non-destructive Testing	639
Testing and Characterization	665
Simulation and Testing	703
Physical Mechanisms and Methods	727
Advanced Methods and Applications	761
Polymeric Materials	815
Ceramics and Glass	833
Diamond, Wide Bandgap Materials, Hard Coatings	855
Electrical and Electronic Properties	889
Microstructure and Material Properties	909
Micromaterials and Environment	923
Materials Characterization and Micromanufacturing	951
Microfabrication, Micromachining, Micromanufacturing	971
Mechatronics, Adaptronics, MEMS	983
Special Applications	1001
6M TV Tower Workshop	1091
German Research Programs	1111
Poster Session	1123

<b>OPENING ADDRESSES</b>	<b>61</b>
Speech at the opening of the MicroMat 2000 Conference <i>MinDir. Dr. Eike Röhling</i>	62
<i>Director-General for Technology and Innovation Policy, German Federal Ministry of Economics and Technology</i>	
Address at the International Conference on Micro Materials »MicroMat 2000« <i>MinDir. Dr. Knut Bauer</i>	66
<i>Director-General for New Technologies and Information Technology, German Federal Ministry of Education and Research</i>	
<b>PLENARY LECTURES</b>	<b>71</b>
Materials science and engineering – A major topic in the future of microelectronic packaging <i>Reichl, H.; Michel, B.; Schubert, A.</i>	72
<i>Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin, Germany</i>	
The future of microelectronics and photonics, and the role of mechanical, materials and reliability engineering <i>Suhir, E.</i>	74
<i>Bell Laboratories, Lucent Technologies, Inc., Murray Hill, USA</i>	
Production of high precision microparts for machines using metallic glass <i>Inoue, A.*; Kawamura, Y.*; Zhang, T.*; Saotome, Y.**</i>	95
<i>* Tohoku University, Sendai, ** Gunma University, Kiryu, Japan</i>	

<b>Internal stresses and lifetime evaluation of PECVD isolating layers</b>	<b>96</b>
<i>Dommann, A.*; Herres, N.**; Krink, M.*; Galiano, J.J.**; Stämpfli, B.***</i>	
* <i>Interstate University of Applied Science Buchs (NTB), Switzerland</i>	
** <i>Fraunhofer-Institut für Angewandte Festkörperphysik (IAF), Freiburg</i>	
*** <i>BPS-NEXTRAL, Grenoble, France</i>	
 <b>NDE for materials characterization in aeronautic and space applications</b>	 <b>102</b>
<i>Baaklini, G.Y.***; Kautz, H.E.***; Gyekenyesi, A.L.**;</i>	
<i>Abdul-Aziz, A.*; Martin, R.E.*</i>	
* <i>Cleveland State University,</i>	
** <i>Ohio Aerospace Institute, Cleveland,</i>	
*** <i>NASA Glenn Research Center, Cleveland, OH, USA</i>	
 <b>Package reliability studies by experimental and numerical analysis</b>	 <b>110</b>
<i>Schubert, A.; Dudek, R.; Michel, B.; Reichl, H.</i>	
<i>Fraunhofer Institute for Reliability and Microintegration, Berlin, Germany</i>	
 <b>Lead-free soldering – Are you ready for this global trend?</b>	 <b>120</b>
<i>Lee, N.-C.</i>	
<i>Indium Corporation of America, Clinton, USA</i>	
 <b>Micro- and nanostructures – preparation and applications</b>	 <b>127</b>
<i>Kassing, R.</i>	
<i>University of Kassel, Germany</i>	
 <b>New developments in nanomaterials</b>	 <b>128</b>
<i>Siegel, R.W.</i>	
<i>Rensselaer Polytechnic Institute, Troy, New York, USA</i>	
 <b>Review of industrial applications of CVD diamond</b>	 <b>129</b>
<i>Sussmann, R.S.; Brandon, J.R.; Pickles, C.S.J.; Whitehead, A.J.</i>	
<i>De Beers Industrial Diamonds (UK) Ltd., Charters, Sunninghill, Ascot, Berkshire, U.K.</i>	
 <b>Dicing challenges in microelectronics and micro electro-mechanical systems (MEMS)</b>	 <b>141</b>
<i>Gatzen, H.H.</i>	
<i>Hanover University, Germany</i>	

Materials problems in high temperature electronics <i>Sharp, R.</i>	147
<i>HITEN Office, AEA Technology, Abingdon, U.K.</i>	
BGA, flip-chip and CSP solder joint reliability <i>Clech, J.-P.</i>	153
<i>EPSI Inc., Montclair, USA</i>	
FEA modeling of FCOB assembly solder joint reliability <i>Pang, H.L.J.; Chong, Y.R.</i>	159
<i>Nanyang Technological University, Singapore</i>	
Properties, characterisation and challenges of semiconducting polymer applications <i>Köhler, A.</i>	167
<i>Cavendish Laboratory, University of Cambridge, Cambridge, U.K.</i>	
Non-equilibrium processing of thin Si films via pulsed laser irradiation <i>Im, J.S.</i>	173
<i>Columbia University, New York, USA</i>	
Study of thermal deformation in underfilled flip-chip packages using high-resolution Moiré interferometry <i>Miller, M.R.; Mohammed, I.; Dai, X.*; Ho, P.S.</i>	174
<i>University of Texas at Austin,</i> * <i>Hewlett Packard, Palo Alto, USA</i>	
Application of fracture mechanics for next-generation packaging structures <i>Sitaraman, S.K.; Xie, W.; Sundararaman, V.; Harries, R.J.</i>	180
<i>Georgia Institute of Technology, Atlanta, USA</i>	
Future developments in electrically conductive adhesives technology <i>Morris, J.E.</i>	181
<i>State University of New York at Binghamton, USA</i>	

<b>Micromaterials: Materials science in small dimensions</b>	<b>187</b>
<b>Arzt, E.*; Kraft, O.*; Dehm, G.**</b>	
* Max-Planck-Institut für Metallforschung, Stuttgart,	
** University of Stuttgart, Germany	
<b>Highly parallel mass fabrication and assembly of microdevices</b>	<b>188</b>
<b>Ehrfeld, W.; Begemann, M.; Berg, U.; Lohf, F.; Michel, F.; Nienhaus, M.</b>	
<i>Institut für Mikrotechnik Mainz GmbH, Germany</i>	
<b>Development of contact and wiring systems for high temperature sensor applications</b>	<b>196</b>
<b>Gessner, T.*.***; Kaufmann, C.*; Hoffmann, R.*; Gottfried, K.*; Wiemer, M.**</b>	
* Chemnitz University of Technology,	
** Fraunhofer Institute of Reliability and Microintegration, Chemnitz, Germany	
<b>Process and mechanical behavior of micro and nano materials</b>	<b>198</b>
<b>Lu, J.</b>	
<i>Université de Technologie de Troyes, France</i>	
<b>Micromechanical actuators based on shape memory effect</b>	<b>200</b>
<b>Büttgenbach, S.; Bütefisch, S.; Lester-Schädel, M.; Wogersien, A.</b>	
<i>Technical University of Braunschweig, Germany</i>	
<b>Thermo-mechanical reliability of microcomponents</b>	<b>206</b>
<b>Dudek, R.; Schubert, A.; Michel, B.</b>	
<i>Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin, Germany</i>	

## PACKAGING MATERIALS

	215
Thin-film metal cantilever springs by stress control <i>Smith, D.L.</i> <i>NanoNexus, Inc., San Jose, USA</i>	216
Molecular modeling and discrete element modeling applied to the microelectronics packaging industry <i>Iwamoto, N.E.*; Nakagawa, M.**</i> * <i>Honeywell, Electronic Materials, San Diego,</i> ** <i>Colorado School of Mines, Golden, USA</i>	222
Mixed mode interfacial fracture toughness investigations for thermo-mechanical reliability enhancement of plastic packages <i>Auersperg, J.***; Kieselstein, E.****; Michel, B.*</i> * <i>Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin,</i> ** <i>AMIC Angewandte Micro-Messtechnik GmbH, Rangsdorf,</i> *** <i>CWM Chemnitzer Werkstoffmechanik GmbH, Chemnitz, Germany</i>	228
New MoCu and WCu MIM-materials designed for heat dissipation purposes in RF packages <i>Müllers, J.*; Knüwer, M.**; Wichmann, K.-H.****; Hager, W.***</i> * <i>DaimlerChrysler Research, Dornier GmbH, Friedrichshafen,</i> ** <i>Fraunhofer Institute Production Technology and Materials Research (IFAM), Bremen,</i> *** <i>DaimlerChrysler Aerospace AG, Ulm, Germany</i>	232
Manufacturing a CSP at wafer level <i>Simon, J.; Wolf, J.; Kallmayer, Ch.; Töpper, M.; Reichl, H.</i> <i>Technische Universität Berlin,</i> <i>Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin, Germany</i>	236
3D wafer level packaging <i>Savastiouk, S.*; Siniaguine, O.*; Korczynski, E.*; Tilenschi, M.**</i> * <i>Tru-Si Technologies, Sunnyvale, USA</i> ** <i>Semicomnect, Munich, Germany</i>	240

Wafer level flip chip packaging <i>Tong, Q.K.; Ma, B.; Savoca, A.</i> National Starch and Chemical Company, Bridgewater, USA	244
Low cost bumping on waferlevel for 300 mm wafer <i>Oppert, T.; Teutsch, T.; Zabel, E.</i> Pac Tech – Packaging Technologies GmbH, Nauen, Germany	245
Microstructure characterization and mechanical properties of Mo-Cu composite for electronic packaging applications <i>Kocdemir, B.; Fecht, H.-J.; Wichmann, K.-H.*</i> Ulm University, * DaimlerChrysler Aerospace AG, Ulm, Germany	251
Study of thermal deformation in BGA assemblies using FEM method <i>Zhang, L.F.*; Wang, W.N.**; Wu, Y.P.*</i> * Huazhong University of Science and Technology, Wuhan, ** Capital Normal University, Beijing, P.R. China	255
Use of alternative materials for packaging of sensors and MCMs <i>Rentsch, A.*; Wilde, J.**</i> * DaimlerChrysler AG, Research and Technology, Frankfurt/Main, ** University of Freiburg, IMTEK, Freiburg, Germany	259
Powder injection moulded aluminium nitride for packaging of mm-wave circuits <i>Fandel, M.*; Hager, W.**; Schäfer, W.*; Wichmann, K.-H.**</i> * DaimlerChrysler Research and Technology/Dornier, Friedrichshafen, ** DaimlerChrysler Aerospace AG, Ulm, Germany	265
Mechanical characterisation and simulation of packaging polymer curing <i>Ernst, L.J.*; van 't Hof, C.*; Yang, D.G.*; Kiasat, M.S.*;</i> <i>Zhang, G.Q.**; Bressers, H.J.L.**; Caers, J.F.J.**; den Boer, A.W.J.**;</i> <i>Janssen, J.**</i> * Delft University of Technology, ** Philips, Eindhoven, The Netherlands	269

Materials for molding processes in microsystems technology Piotter, V.; Gietzelt, T.; Hanemann, T.; Ruprecht, R.; Hausselt, J. Forschungszentrum Karlsruhe GmbH, Germany	274
BGA packaging technology for rapid prototyping supported by advanced analytics Becker, K.-F.**; Ehrlich, R.*; Ansorge, F.*; Aschenbrenner, R.*; Krause, F.*; Kämpfe, B.*; Reichl, H.* * Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin, ** Forschungsschwerpunkt Technologien der Mikroperipherik der TU Berlin, Germany	278
Investigation of interface cracking in electronic packages Kieselstein, E.*; Seiler, B.*; Winkler, T.*; Dudek, R.**; Auersperg, J.**; Schubert, A.**; Schneider, W.***; Michel, B.** * Chemnitzer Werkstoffmechanik GmbH, Chemnitz, ** Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin, *** MPD GmbH, Dresden, Germany	285
Flex, rigid, and ceramic CSP - lifetime behavior Albrecht, H.-J.*; Jendrny, J.**; Müller, W.H.***; Schwarz, B.*; Teichmann, H.*; Tilgner, R.**** * Siemens AG, Berlin, ** Universität-GH Paderborn, Germany *** Heriot-Watt University, Edinburgh, U.K. **** Siemens AG, München, Germany	289
Reliability risk assessment of organic flip chip pin grid array package under thermal and mechanical loading conditions Goh, T.J. Intel Products, Kulim, Malaysia	293
Modeling of the deformation behavior of a flip chip underfill for finite element analyses Feustel, F.; Meusel, E. Dresden University of Technology, Germany	302

<b>Modelling of material properties for advanced packaging</b>	<b>306</b>
<b>Bitz, C.*; Becker, K.**; Wilde, J.***</b>	
* DaimlerChrysler AG, Research and Technology, Frankfurt a.M.,	
** University of Applied Science Bingen,	
*** University of Freiburg, Germany	
<b>microDAC strain measurement for FEA support</b>	<b>311</b>
<b>Vogel, D.*; Gollhardt, A.*; Schubert, A.*; Kühnert, R.**; Michel, B.*</b>	
* Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin,	
** K&T Meßsysteme GmbH, Chemnitz, Germany	
 <b>NANOMATERIALS</b>	
<b>Nanostructured materials for microtechniques</b>	<b>315</b>
<b>Schmidt, H.</b>	
<i>Institut für Neue Materialien gem. GmbH, Saarbrücken, Germany</i>	
<b>Nano- and microscale materials in microreactors</b>	<b>317</b>
<b>Hessel, V.*; Ehrfeld, W.*; Löwe, H.*; Schiewe, J.*; Donnet, M.**</b>	
* Institut für Mikrotechnik Mainz GmbH, Germany	
** Ecole Polytechnique Fédérale de Lausanne, Switzerland	
<b>Sol-gel pastes for conductive fine line printing</b>	<b>321</b>
<b>Kalleder, A.; Kreutzer, R.; Mennig, M.; Schmidt, H.</b>	
<i>Institut für Neue Materialien gem. GmbH, Saarbrücken, Germany</i>	
<b>Preparation of micro patterns with profile heights up to 100 µm by sol gel technology</b>	<b>322</b>
<b>Mennig, M.; Gier, A.; Schmidt, H.</b>	
<i>Institut für Neue Materialien gem. GmbH, Saarbrücken, Germany</i>	
<b>Nanoparticles for sensors:</b>	
<b>Technology, basic understanding and applications</b>	<b>323</b>
<b>Weimar, U.</b>	
<i>University of Tübingen, Germany</i>	

Nanocrystalline hydride electrode materials 324  
*Jurczyk, M.*  
*Poznan University of Technology, Poland*

## MICRO- AND NANOPROBE TECHNIQUES 327

Local scanning probe methods 328

*Güntherodt, H.-J.*

*University of Basel, Switzerland*

Scanning probe microscopy in semiconductor failure analysis 329

*Ebersberger, B.; Olbrich, A.; Boit, C.*

*Infineon Technologies AG, Munich, Germany*

Sensors for scanning probe microscopy (SPM) 335

*Oesterschulze, E.; Kassing, R.*

*University of Kassel, Germany*

Voltage contrast measurements with an electric force 336

microscope based test system

*Behnke, U.; Mertin, W.; Kubalek, E.*

*Gerhard-Mercator-Universität Duisburg, Germany*

Quantitative contact spectroscopy by atomic-force 340

acoustic microscopy

*Amelio, S.; Rabe, U.; Kester, E.; Hirsekorn, S.; Arnold, W.*

*Fraunhofer-Institute for Nondestructive Testing,*

*Saarbrücken, Germany*

Thermomicroscopy of materials and devices at nanometer 344

dimensions

*Feege, G.B.M.\*; Becker, G.\*\*; Engemann, J.\*; Boit, C.\*\*; Balk, L.J.\**

*\* Bergische Universität Wuppertal,*

*\*\* Infineon Technologies, München, Germany*

## HIGH TEMPERATURE ELECTRONICS AND TERMAL PROBLEMS

349

- Thermal management with novel materials 350  
*Johnston, C.; Young, R.; Crossley, A.*  
*AEA Technology plc, Didcot, U.K.*

- High temperature fiber optic thermal device 356  
*Herringer, J.H.; Djeu, N.*  
*University of South Florida, Tampa, USA*

- A review of fully-depleted SOI CMOS technology for microsystems 357  
*Demeûs, L.; Delatte, P.; Dessard, V.; Adriaensen, S.; Renaux, C.; Flandre, D.*

*Université catholique de Louvain, Louvain-la-Neuve, Belgium*

- Modelling of thermal aspects of power electronic assemblies 363  
*Poech, M.H.*

*Fraunhofer-Institut für Siliziumtechnologie, Itzehoe, Germany*

- Interconnection materials for flip chip technology in high  
temperature automotive applications – A comparative study 367  
*Riepl, T.; Lugert, G.*

*Siemens Automotive, Regensburg, Germany*

- Reliability requirements for microtechnologies used in  
automotive applications 371

- Wondrak, W.\*; Constapel, R.\*; Senske, W.\*; Wilde, J.\*\**  
\* *DaimlerChrysler AG, Research and Technology, Frankfurt,*  
\*\* *University of Freiburg, Germany*

## THIN FILMS AND LAYERS

375

- Atomic diffusion and phase stability in thin films 376  
*Greer, A.L.*  
*University of Cambridge, U.K.*

A new method of quantitative evaluation for the adhesive toughness of thin films and substrates <i>Kamiya, S.; Inoue, A.; Saka, M.; Abé, H.</i> <i>Tohoku University, Sendai, Japan</i>	377
Effect of bottom electrodes on microstructures and electrical properties of sol gel derived $\text{Pb}(\text{Zr}_{0.53}\text{Ti}_{0.47})\text{O}_3$ thin film <i>Wang, Z.J.; Chu, J.R.; Maeda, R.</i> <i>Mechanical Engineering Laboratory, AIST, MITI, Tsukuba, Ibaraki, Japan</i>	381
Determination of intrinsic stress during the growth of Fe(Zr) thin films <i>Grob, A.*; Herr, U.*; Samwer, K.**</i> * Universität Augsburg, ** Universität Göttingen, Germany	385
Paraelectric film as microwave phase shifter <i>Poplavko, Y.; Prokopenko, Y.; Baik, S.</i> <i>National Technical University of Ukraine, Kiev, Ukraine</i>	389
<b>INDENTATION METHODS, LAYERS, INTERFACES</b> <span style="float: right;">391</span>	
The fictitious indentation depth-load trajectory as a new approach for determining thin film mechanical properties without substrate effects <i>Huber, N.*; Tsakmakis, C.**</i> * Forschungszentrum Karlsruhe, ** Technische Universität Darmstadt, Germany	392
Dislocation nucleation during nanoindentation <i>Lorenz, D.*; Johansen, H.**; Grau, P.*</i> * Martin-Luther-University Halle-Wittenberg, ** Max-Planck-Institute for Microstructure Physics, Halle, Germany	396

Effects of work-hardening characteristics on evaluating flow properties from indentation load-depth curve <i>Ahn, J.-H.; Jeon, E.-c.; Choi, Y.; Lee, Y.-H.; Kwon, D.</i> <i>Seoul National University, Korea</i>	400
Texture and internal stresses in FeCo-layers for microinductors <i>Dieter, S.; Pyzalla, A.; Reimers, W.</i> <i>Hahn-Meitner-Institut, Berlin, Germany</i>	404
X-ray texture and residual stress analysis on photoactivated electrolessly plated Cu-layers <i>Kämpfe, A.*; Löhe, D.*; Stolle, T.**; Kämpfe, B.***</i> * Universität Karlsruhe (TH), ** Technische Universität Berlin, *** Fraunhofer Institute for Reliability and Microintegration (IZM), <i>Berlin, Germany</i>	408
Interface studies between epoxy and recycled rubber <i>Sipahi-Saglam, E.; Kaynak, C.; Akovali, G.</i> <i>Middle East Technical University, Ankara, Turkey</i>	413
<b>SENSOR- AND ACTUATOR MATERIALS</b> <span style="float: right;">417</span>	
Carbon components for micro-world machines <i>Libera, J.A.; Gogotsi, Y.</i> <i>University of Illinois at Chicago, USA</i>	418
Development and applications of sensors for deep space explorations <i>Kolawa, E.</i> <i>Jet Propulsion Laboratory, Pasadena, USA</i>	419
Silicon three-axial tactile sensor for micromaterial characterisation <i>Bütefisch, S.*; Büttgenbach, S.*; Kleine-Besten, T.**; Loheide, S.**;</i> <i>Brand, U.**</i> * <i>TU Braunschweig,</i> ** <i>Physikalisch-Technische Bundesanstalt, Braunschweig, Germany</i>	420

Investigations and development of tactile ferropiezoelectric array sensors <i>Todorova, V.</i>	426
<i>Technical University, Gabrovo, Bulgaria</i>	
<b>SOLDER MATERIALS, BONDING, JOINING</b>	<b>429</b>
Numerical analysis of meniscus geometry and wetting force for wettability evaluation in reflow-mode wetting balance test <i>Yasuda, K.; Kitada, T.; Fujimoto, K.; Nakata, S.</i>	430
<i>Osaka University, Japan</i>	
The influence of surface oxide films on hardness and thermosonic wire bonding of Al bondpads <i>Petzold, M.*; Berthold, L.*; Katzer, D.*; Knoll, H.*; Memhard, D.*; Meier, P.**; Lang, K.-D.**</i>	434
* Fraunhofer-Institut Werkstoffmechanik Freiburg und Halle, ** Fraunhofer-Institut Zuverlässigkeit und Mikrointegration (IZM), Berlin, Germany	
Patterning of SOI-materials for fabrication of resonator systems using waferbonding approaches <i>Wiemer, M.*; Hiller, K.**; Gessner, T.*.**</i>	438
* Fraunhofer Institute of Reliability and Microintegration, Chemnitz, ** Chemnitz University of Technology, Germany	
Laser beam micro joining for electronics industry <i>Olowinsky, A.; Legewie, F.; Kramer, T.; Bosse, L.; Gillner, A.; Poprawe, R.</i>	442
<i>Fraunhofer-Institut für Lasertechnik, Aachen, Germany</i>	
An assessment of mechanical properties of heterogeneous weld joint with thin layer <i>Ranatowski, E.</i>	444
<i>Technical University, Bydgoszcz, Poland</i>	

Magnitude and location of strain in SMT solder joints <i>Grossmann, G.; Affolter, C.</i>	448
Swiss Federal Institute for Materials Testing and Research, Duebendorf, Switzerland	
Correlation of reliability with the mechanical properties of leadfree solders <i>Reitlinger, C.E.; Dittes, M.; Bergmann, H.W.</i>	452
University of Bayreuth, Germany	
A constitutive material model of eutectic SnPb flip chip solder for ANSYS® <i>Wiese, S.; Feustel, F.; Rzepka, S.; Meusel, E.</i>	453
Dresden University of Technology, Germany	
Finite-element-investigations on testing devices for solder joint reliability evaluation <i>Kaulfersch, E.*; Vogel, J.**; Sommer, J.-P.***; Michel, B.***</i>	457
* AMIC GmbH Berlin/Rangsdorf, ** CWM GmbH Chemnitz, *** Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin, Germany	
Development and application of ultrafinepitch solder paste for advanced microelectronic packaging <i>Einenkel, A.*; Paproth, A.**; Schneider, W.***; Berek, H.*;</i> <i>Pachschwöll, H.*</i>	459
* FNE Forschungsinstitut für Nichteisen-Metalle Freiberg GmbH, ** TU Dresden, *** Microelectronic Packaging Dresden GmbH, Germany	
<b>STRESS, STRAIN, RELIABILITY</b>	<b>463</b>
Non self-similar crack extension: to »kink« or not to »kink«? <i>Lo, K.W.; Zhong, K.; Tamilselvan, T.</i>	464
The National University of Singapore, Singapore	

**Modeling and testing of strength and fracture of  
microelectronic materials and components** 471  
**Goldstein, R.V.**

*The Institute for Problems in Mechanics, The Russian Academy of  
Sciences, Moscow, Russia*

**Fracture electronics and thermo-mechanical compatibility  
(TMC) of microcomponents in high tech systems** 472  
**Michel, B.\*; Winkler, T.\*\***

\* *Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin,*

\*\* *Chemnitzer Werkstoffmechanik GmbH, Chemnitz, Germany*

**Stress-induced lateral deflections of microstructures** 476  
**Küchler, M.\*; Knöfler, R.\*\*; Steiniger, C.\*\*; Raschke, T.\*\*;  
Gessner, T.\*\*\*; Dudek, R.\*; Döring, R.\*\*\***

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**On a deformation of the polycrystalline structure** 480  
**Berka, L.; Horečka, L.**  
*Czech Technical University Prague, Czech Republic*

## **MECHANICAL PROPERTIES AND RELIABILITY** 487

**Finite element techniques for flaw analyses in  
piezoelectric micro-components** 488  
**Kuna, M.; Scherzer, M.; Ricoeur, A.**

*Freiberg University of Mining and Technology, Germany*

**Fatigue testing of thin metal films on substrates** 496  
**Kraft, O.; Schwaiger, R.; Wellner, P.**

*Max-Planck-Institut für Metallforschung und  
Universität Stuttgart, Germany*

A resonance method for the determination of Young's modulus and residual stress of thin microstructures <i>Mehner, J.; Kehr, K.; Schröter, B.; Kaufmann, C.; Dötzel, W.; Gessner, T.</i>	497
<i>Chemnitz University of Technology, Germany</i>	
R-curve behavior of BaTiO <sub>3</sub> - and PZT-ceramics under the influence of an electric field <i>Niefanger, R.; Kolleck, A.; Schneider, G.A.</i>	501
<i>Technische Universität Hamburg-Harburg, Germany</i>	
Mechanical and thermomechanical properties of Al-SiC-MMC <i>Lefranc, G.; Degischer, H.P.*; Mitic, G.; Licht, T.**</i>	506
<i>Siemens AG, Corporate Technology, Munich, Germany</i>	
* <i>Vienna Univ. of Technology, Austria</i>	
** <i>eupec GmbH, Warstein, Germany</i>	
Lifetime investigations of directly wafer-bonded samples under static and cyclic loading <i>Bagdahn, J.; Petzold, M.; Sommer, E.</i>	510
<i>Fraunhofer Institut für Werkstoffmechanik, Freiburg und Halle, Germany</i>	
Database for materials in micro systems <i>Villain, J.*; Müller, T.**; Michel, B.***; Totzauer, W.**</i>	514
* <i>University of Applied Sciences Augsburg,</i>	
** <i>University of Applied Sciences Mittweida,</i>	
*** <i>Fraunhofer IZM Berlin, Germany</i>	
Determination of mechanical and tribological properties in the nm-range with the Hysitron TriboScope <i>Hangen, U.D.</i>	518
<i>SURFACE, Hückelhoven, Germany</i>	
A study of heel crack failures in wire bonds under mechanical cycling <i>Seliger, N.*; Ramminger, S.*; Franke, T.*; Wachutka, G.**</i>	522
* <i>Siemens AG, Corporate Technology, Munich,</i>	
** <i>Munich University of Technology, Germany</i>	

Fatigue life and crack growth properties of micro-sized Ni-P amorphous alloy specimens	526
<i>Takashima, K.*; Maekawa, S.*; Ichikawa, Y.*; Shimojo, M.*; Higo, Y.*; Sugiura, S.**; Swain, M.V.***</i>	
* Tokyo Institute of Technology,	
** Nissei Sangyo, Tokyo, Japan	
*** The University of Sydney, Australia	
Relation between accelerated ageing tests and actual operation: finite element simulation evaluation	530
<i>Thébaud, J.-M.*; Woigard*, E.; Zardini, C.*; Sommer, K.-H.**</i>	
* Université Bordeaux, Talence, France	
** formerly with Infineon (EUPEC GmbH, Warstein, Germany)	
A study on rupture behavior of SMT solder joint with mechanical heterogeneity	536
<i>Wang, L.*; Fang, H.*; Qian, Y.*; Wang, G.**</i>	
* National Key Laboratory of Advanced Welding Production Technology of Harbin Institute of Technology, Harbin,	
** Shanghai Institute of Metallurgy of Academy of Sciences of China, P.R. China	
Fracture mechanics characterisation of epoxy resins with Mini-Compact Tension (CT)-specimens	537
<i>Walter, H.*; Bierögel, C.**; Grellmann, W.**; Fedtke, M.**; Michel, B.***</i>	
* AMIC GmbH, Berlin/Rangsdorf,	
** Martin Luther-Universität , Halle-Wittenberg,	
*** Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin, Germany	
<b>DAMAGE AND FAILURE MECHANISMS, CRACK, FRACTURE, FATIGUE</b>	<b>541</b>
Cohesive surface modeling of fracture	542
<i>Needleman, A.</i>	
Brown University, Providence, USA	

Damage modelling via bi-modal surface energies <i>Del Piero, G.</i> Università di Ferrara, Italy	548
Environmentally assisted damage of metals with covering <i>Balueva, A.V.</i> Georgia Institute of Technology, Atlanta, USA	549
Multi-level modelling of heterogeneous micro materials <i>Kouznetsova, V.; Brekelmans, W.A.M.; Geers, M.G.D.; Baaijens, F.P.T.</i> Eindhoven University of Technology, The Netherlands	550
FE-Simulation of anisotropic damage development in creep process <i>Qi, W.; Brocks, W.</i> GKSS Research Center, Geesthacht, Germany	554
The »size effect« on the fatigue- and fracture properties of thin metallic foils and wires <i>Hadrboletz, A.; Weiss, B.; Khatibi, G.</i> University of Vienna, Austria	558
Effect of intermetallic compound layer development on mechanical strength of 63Sn-37Pb solder joints <i>Kishimoto, K.*; Masuda, K.*; Omiya, M.*; Shibuya, T.*; Amagai, M.**</i> * Tokyo Institute of Technology, ** Texas Instruments Japan, Oita, Japan	560
Submicrometer notch machining by FIB and fracture and fatigue behavior in silicon microelements <i>Minoshima, K.*; Terada, T.**; Komai, K.*</i> * Kyoto University, ** Nomura Research Institute, Ltd., Tokyo, Japan	566
Fracture strength of GaAs wafers <i>Schaper, M.*; Jurisch, M.**; Klauß, H.-J.*; Balke, H.*; Bergner, F.*; Hammer, R.*; Winkler, M.*</i> * Dresden University of Technology, ** Freiberger Compound Materials GmbH, Germany	570

Fracture toughness measurements of micro-sized Ni-P amorphous alloy specimens <i>Ogura, A.*; Ichikawa, Y.*; Shimojo, M.*; Takashima, K.*; Higo, Y.*; Swain, M.V.**</i>	574
* Tokyo Institute of Technology, Japan	
** University of Sydney, Australia	
Measurement of strain fields in the micron range <i>Onraet, S.; Luff, D.; Geers, M.; Vellinga, W.P. Eindhoven University of Technology, The Netherlands</i>	578
Numerical analysis of an electronic structure bearing deep cracks <i>Eberle, A.; Sievert, R. Federal Institute for Materials Research and Testing (BAM), Berlin, Germany</i>	582

<b>OPTICAL METHODS</b>	<b>587</b>
Grating and Moiré methods for micro-measurement <i>Asundi, A. Nanyang Technological University, Singapore</i>	588
Recovery of fringe pattern in holographic interferometry <i>Tatasciore, P.*/**; Meyer-Piening, H.-R.** * Holtec GmbH, Zug, ** Swiss Federal Institute of Technology (ETH), Zurich, Switzerland</i>	589
New investigations in materials research by Confocal Laser Scanning Microscopy <i>Kunath-Fandrei, G.; Faust, W.*; Ullmann, P.; Michel, B.* Carl Zeiss Jena GmbH, Jena, * Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin, Germany</i>	595

A method of transfer relations – new perspectives in physical grounds of near-field optics	599
<i>Barabanenkov, Y.N.*; Barabanenkov, M.Y.**</i>	
* Institute of Radioengineering and Electronics RAS, Moscow,	
** Institute of Microelectronics Technology RAS, Chernogolovka, Russia	
Monitoring of surface homogeneity of optical parameters of thin films	604
<i>Urbánek, M.; Spousta, J.; Jiruše, J.; Zlámal, J.; Chmelík, R.; Dittrichová, L.; Nebojsa, A.*; Šikola, T.</i>	
<i>Brno University of Technology,</i>	
<i>* Masaryk University, Brno, Czech Republic</i>	
UNIDAC - cross correlation based deformation analysis at digitised micrographs to study material behaviour and parameters in MST	610
<i>Dost, M.; Kieselstein, E.; Erb, R.; Seiler, B.; Vogel, J.; Bombach, C.*; Großer, V.*; Vogel, D.*; Michel, B.*</i>	
<i>Chemnitzer Werkstoffmechanik GmbH, Chemnitz,</i>	
<i>* Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin, Germany</i>	
3D-microscope-ESPI: potential for displacement analysis of micromechanic components	615
<i>Yang, L.; Schubach, H.; Wegner, R.; Ettemeyer, A.</i>	
<i>Dr. ETTEMEYER GmbH &amp; Co., Neu-Ulm, Germany</i>	
Optical crack tracing - A new method for the automatic determination of fracture toughness for crack initiation and propagation	618
<i>Uhlig, C.*; Kahle, O.*; Wieneke, B.**; Bauer, M.*</i>	
<i>* Fraunhofer-Institute for Reliability and Microintegration, Branch Lab Teltow,</i>	
<i>** LaVision 2D-Meßtechnik GmbH, Göttingen, Germany</i>	
The measurement of thermal deformation in BGA assemblies using real-time holographic interferometry	630
<i>Wang, W.N.*; Wu, Y.P.**; Zhang, L.F.**; Ai, L.*</i>	
<i>* Capital Normal University, Beijing,</i>	
<i>** Huazhong University of Science and Technology, Wuhan, P.R. China</i>	

Evaluation and testing of microsystems using optical methods <i>Großer, V.; Bombach, C.; Gentzsch, S.; Hillmann, V.; Sommer, J.-P.; Michel, B.</i>	634
<i>Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin, Germany</i>	

## NON-DESTRUCTIVE TESTING 639

Conducting Atomic Force Microscopy – A new tool for the quantitative electrical characterization of thin oxides at a nanometer scale length <i>Olbrich, A.; Ebersberger, B.; Boit, C.</i>	640
--	-----

*Infineon Technologies AG, Munich, Germany*

Analysis of the injection level and temperature dependence of carrier lifetime by microwave photoconductivity decay <i>Frohnmeyer, A.***; Niedernosteide, F.-J.*; Schulze, H.-J.*; Tütto, P.**; Pavelka, T.**; Wachutka, G.***</i>	644
---	-----

\* Siemens AG, Corporate Technology, Munich, Germany

\*\* Semiconductor Physics Laboratory RT, Budapest, Hungary

\*\*\* Munich University of Technology, Munich, Germany

Contactless, spatially resolved current detection at megahertz bandwidth via the implementation of the heterodyne mixing technique <i>Bae, S.; Schiemann, K.; Mertin, W.; Kubalek, E.</i>	648
--	-----

*Gerhard-Mercator-Universität Duisburg, Germany*

Nondestructive evaluation of fracture characteristics by quantification of Barkhausen noise method and microstructure analysis <i>Kim, D.-W.; Kwon, D.</i>	652
---	-----

*Seoul National University, Seoul, Korea*

Characterization of transition metal oxides by ultrasonic microscopy <i>Maurer, D.; Leue, A.; Heichele, R.; Müller, V.</i>	656
---	-----

*Universität Augsburg, Germany*

Microstructural characterization of SiC/Al interface after  
quenching X-ray diffraction, TEM and AFM

660

*Coniglione, S.; Patuelli, C.; Tognato, R.*

*Universita' di Bologna, Italy*

## TESTING AND CHARACTERIZATION

665

Tensile testing of MEMS materials

666

*Sharpe Jr., W.N.*

*Johns Hopkins University, Baltimore, MA, USA*

Nanotribological characterization of brittle surfaces

667

*Enders, S.; Grau, P.; Berg, G.*

*Martin-Luther-University, Halle/Saale, Germany*

Determination of mechanical parameters of solder materials  
using the miniature measuring method »Small Punch Test«

671

*Nguyen, v.S.; Herrmann, K.P.; Müller, W.H.\*; Albrecht, H.-J.\*\*;  
Foulds, J.\*\*\**

*Laboratorium für Technische Mechanik, Paderborn, Germany*

\* Heriot-Watt University, Edinburgh, U.K.

\*\* Siemens AG, Berlin, Germany

\*\*\* Failure Analysis Associates, Menlo Park, USA

Reliability investigations of vibration excited circuit boards

675

*Rümmler, N.\*; Schnitzer, R.\*\*; Döring, R.\*\*; Kaulfersch, E.\*\*\*;  
Faust, W.\*\*\*\*; Michel, B.\*\*\*\**

\* AMITRONICS Angewandte Mikromechatronik GmbH, Seefeld,

\*\* Chemnitzer Werkstoffmechanik GmbH,

\*\*\* AMIC Angewandte Micro-Messtechnik GmbH, Rangsdorf,

\*\*\*\* Fraunhofer Institute for Reliability and Microintegration (IZM),  
Berlin, Germany

Breakdown of elasticity in Copper and Aluminium interconnects

679

*Schreiber, J.; Melov, V.G.; Herms, M.*

*Fraunhofer Institute of Non-destructive Testing, Dresden, Germany*

Nano-writing with atomic force microscopy <i>Crossley, A.*; Mapledoram, L.*; Sofield, C.*; Johnston, C.*; Myhra, S.**</i>	683
* AEA Technology plc, Harwell, U.K.	
** Griffith University, Queensland, Australia	
 μ-XRF – A new powerful analytic tool for microstructures <i>Haschke, M.*; Kämpfe, B.**</i>	 689
* X-Ray Analytics and Measurement Technology, Taunusstein,	
** Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin, Germany	
 Modular loading and measuring system for material characterisation of microcomponents <i>Vogel, J.*; Dost, M.**; Seebacher, S.***; Fassler, R.****; Köpp, N.*****; Döring, R.**; Sommer, J.-P.*****; Osten, W.***; Michel, B.*****</i>	 690
* Angewandte Micro-Messtechnik GmbH, Rangsdorf,	
** Chemnitzer Werkstoffmechanik GmbH,	
*** Bremer Institut fuer Angewandte Strahltechnik,	
**** Jenoptik Laser.Optik.Systeme GmbH, Jena,	
***** VEW Vereinigte Elektronikwerkstätten GmbH, Bremen,	
***** Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin, Germany	
 Residual stress determination in microsystems using X-ray diffraction <i>Kämpfe, B.*; Kämpfe, A.**; Auerswald, E.*; Kassem, M.E.***</i>	 696
* Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin,	
** University of Karlsruhe (TH), Germany	
*** Assiut University, Egypt	
 Nanofocus CT - A new dimension in radioscopic inspection on micro materials <i>Hanke, R.*; Baumbach, T.**</i>	 700
* Fraunhofer Development Center for X-Ray Technology, Erlangen/Saarbrücken,	
** Fraunhofer Institute for Nondestructive Testing, Dresden, Germany	

**SIMULATION AND TESTING****703**

Investigation of microshaped samples of metallic materials and  
carbon fibers

704

*Schneider, H.; Huber, K.; Aktaa, J.*

*Forschungszentrum Technik und Umwelt, Karlsruhe, Germany*

Electromechanical transducer and stochastic damages

705

*Will, P.*

*University of Applied Sciences Mittweida, Germany*

Influence of specimen dimensions on creep behavior of solder material

710

*Villain, J.\*; Brueller, O.\*\**

*\* University of Applied Sciences Augsburg,*

*\*\* Technical University München, Garching, Germany*

State-of-the-art micro materials models in MINIMOS-NT

714

*Palankovski, P.; Selberherr, S.*

*TU Vienna, Austria*

An analysis of crack nucleation in fibre-reinforced concrete

718

*Bayard, O.; Plé, O.*

*Ecole normale Supérieure de Cachan, France*

Some remarks about indentation tests with spherical indenters

722

*Brämer, K.; Chudoba, T.; Hermann, I.*

*Technical University Chemnitz, Germany*

**PHYSICAL MECHANISMS AND METHODS****727**

Thermal-fatigue kinetics in SMC solder joints by SEM/EDS fractography

728

*Glickman, E.\*; Davidson, J.\*\*; Ichilov, O.\*\**

*\* Tel Aviv University,*

*\*\* Telrad Communication and Electronic Industries Ltd., Lod, Israel*

Gradient-enhanced macroscopic constitutive principles for the mechanical description of microstructures <i>Geers, M.G.D.; Kouznetsova, V.; Brekelmans, W.A.M.; Peerlings, R.H.J.</i>	734
<i>Eindhoven University of Technology, The Netherlands</i>	
Stability of flat boundary under surface diffusion <i>Morozov, N.*; Pitkin, P.**</i>	738
* Institute of Mathematics and Mechanics, St.-Peterburg, ** Marine Technical University, St.-Peterburg , Russia	
The aluminium film plastic deformation analysis during local anodic oxidation <i>Vrublevsky, I.; Parkoun, V.</i>	739
<i>Belarussian State University of Informatics and Radioelectronics, Minsk, Belarus</i>	
Characterization and aging of optical fiber Bragg gratings <i>Nellen, P.M.; Sennhauser, U.</i>	740
<i>EMPA, Swiss Federal Laboratories for Materials Testing and Research, Dübendorf, Switzerland</i>	
Properties of nanocrystalline diamond films deposited in argon microwave plasma <i>Pageler, A. */**; Busmann, H.-G. **; Boseck, S. *</i>	744
* University of Bremen, ** Fraunhofer Institute for Manufacturing and Advanced Materials, Bremen, Germany	
Development of lubricious DLC coatings for microdevices <i>Garcia, A.; Viviente, J.L.; Brizuela, M.; Alonso, F.; Braceras, I.; Oñate, J.I.</i>	748
<i>INASMET, San Sebastián, Spain</i>	
Mechanical properties of electroplated Nickel <i>Fritz, T.; Leuerer, T.; Krueger, C.; Mokwa, W.; Schnakenberg, U.</i>	752
<i>University of Technology Aachen, Germany</i>	

Nanocrystalline wear resistant Ni-W deposited by an environmentally cleaner electroplating process <i>Auerswald, J.*; Croopnick, G.A.**; Wanderka, N.***; Fecht, H.-J.*</i>	756
* University Ulm, Germany	
** Amorphous Technologies International, Laguna Niguel, USA	
*** Hahn-Meitner-Institut Berlin GmbH, Berlin, Germany	
Analytical simulation tools to determine the behavior of bulk and layered substrates <i>Holbery, J.D.; Consiglio, R.</i>	760
Centre Suisse d'Electronique et de Microtechnique SA, Neuchatel, Switzerland	
<b>ADVANCED METHODS AND APPLICATIONS</b>	<b>761</b>
Giant magnetoresistance: basics and applications <i>Shull, R.D.</i>	762
National Institute of Standards and Technology, Gaithersburg, USA	
Qualification of different standard photo resins and new laser sources for micro-stereolithography <i>Tönshoff, H.K.; Alvensleben, F. von; Körber, K.; Beil, A.</i>	763
Laser Zentrum Hannover e.V., Germany	
Design optimization for electroplated micro-springs <i>Leuerer, T.; Krueger, C.; Fritz, T.; Mokwa, W.; Schnakenberg, U.</i>	767
RWTH Aachen, Germany	
Electroless metallization of non-metallic materials and ductility of Ni-P coating <i>Khoperia, T.N.</i>	771
Institute of Physics, Georgian Academy of Sciences, Tbilisi, Georgia	

Optical properties and film stress behavior of Silver reflection coatings for micro mirrors	788
<i>Krujatz, J.; Werner, T.; Kaufmann, C.; Gessner, T.</i>	
<i>TU Chemnitz, Germany</i>	
KOH etch rate and optical properties of ICPECVD silicon nitride	792
<i>Wolf, R.*; Gruska, B.**; Wandel, K.**</i>	
<i>* O.U.T. e.V. Berlin,</i>	
<i>** SENTECH Instruments GmbH Berlin, Germany</i>	
Reliability of soldered Nickel bumps for high temperature application	796
<i>Anhöck, S.*; Ostmann, A.*; Aschenbrenner, R.**; Reichl, H.**</i>	
<i>* Technical University of Berlin,</i>	
<i>** Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin, Germany</i>	
Ion assisted growth of ultrathin diffusion barriers on low dielectric constant polymers	802
<i>Kiene, M.; Abramowitz, P.; Ho, P.S.</i>	
<i>University of Texas at Austin, USA</i>	
Large area surface-relief microstructures for optical applications	806
<i>Boerner, V.; Bläsi, B.; Gombert, A.; Heinzel, A.; Kübler, V.; Niggemann, M. Popp, P.; Wittwer, V.</i>	
<i>Fraunhofer Institute for Solar Energy Systems ISE, Freiburg, Germany</i>	
Thermographical characterisation of the piezoresistive cantilever for scanning probe microscopy	810
<i>Szeloch, R.F.; Gotszalk, T.P.; Rangelow, I.W.*; Grabiec, P.; Radojewski, J.; Janus, P.; Orawski, W.; Pedrak, R.</i>	
<i>Wroclaw University of Technology, Poland</i>	
<i>* University of Kassel, Germany</i>	

<b>POLYMERIC MATERIALS</b>	<b>815</b>
High performance thermosets for microelectronics <i>Bauer, M.</i>	816
<i>Fraunhofer Institute for Reliability and Microintegration (IZM), Branch Lab Polymeric Materials and Composites, Teltow, Germany</i>	
Fabrication and characterization of plastic (PMMA) for inexpensive MEMS components	818
<i>Mietke, S.; Ilgner, J.; Köhler, T.; Wehnert, C.*; Becker, H.**; Gluche, P.***; Fecht, H.-J.****; Werner, M.</i>	
<i>Deutsche Bank AG, Microtechnology Innovation Team, Berlin, * Technical University Berlin, ** JENOPTIK Mikrotechnik GmbH, Jena, *** Gesellschaft für Diamantprodukte mbH, Ulm, **** University of Ulm, Germany</i>	
Condensation and nucleation of noble metals on low-k polymers	822
<i>Zaporojtchenko, V.; Thran, A.; Behnke, K.; Kiene, M.; Strunskus, T.; Faupel, F.</i>	
<i>Universität Kiel, Germany</i>	
Thermo-mechanical testing of polymeric materials under rates of deformation between $10^{-2}$ m/s – $10^{+2}$ m/s	824
<i>Jedicke, O.; Eisenreich, N.</i>	
<i>Fraunhofer Institute ICT, Karlsruhe, Germany</i>	
Lyotropic liquid crystalline polymers – a new thermotropic material	828
<i>Seiboth, A.; Schneider, J.; Fischer, T.; Holzbauer, H.-R.; Kriwanek, J.; Lötzsch, D.; Patzak, A.</i>	
<i>WITEGA – Applied Materials Research, Berlin, Germany</i>	
Measurement of material properties by a modified microDAC approach	829
<i>Vogel, D.; Luczak, F.; Wittler, O.; Gollhardt, A.; Walter, H.; Michel, B.</i>	
<i>Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin, Germany</i>	

<b>CERAMICS AND GLASS</b>	<b>833</b>
CLP-lamination: A new lamination technique to join ceramic green tapes in multilayer processing <i>Roosen, A.</i>	834
<i>University of Erlangen-Nuremberg, Germany</i>	
Photostructurable glasses with integrated wave guides <i>Hecht-Mijic, S.*; Christ, V.*; Straube, B.*; Harnisch, A.*;</i> <i>Mrotzek, S.*; Kucera, U.*; Hüslenberg, D.*; Mollenhauer, O.**</i>	838
<i>* Ilmenau Technical University,</i>	
<i>** Tetra GmbH, Ilmenau, Germany</i>	
Thermal matching of a glass-ceramic-interface for a carbon dioxide sensor <i>Luniak, M.; Wolter, K.-J.</i>	845
<i>Dresden University of Technology, Germany</i>	
Distributed crack propagation in porous ceramic materials <i>Sadowski, T.; Samborski, S.</i>	851
<i>Technical University of Lublin, Poland</i>	
  <b>DIAMOND, WIDE BANDGAP MATERIALS, HARD COATINGS</b>	<b>855</b>
Properties of diamond for sensor applications <i>Jackman, R.B.</i>	856
<i>University College London, U.K.</i>	
The material properties, growth technology and applications of wide bandgap semiconductors for sensors and electronics <i>Chalker, P.R.</i>	857
<i>University of Liverpool, U.K.</i>	

Temperature dependence of Young's modulus and degradation of chemical vapor deposited diamond <i>Mahlich, M.; Fecht, H.-J.; Szucs, F.*; Werner, M.**; Sussmann, R.S.***; Pickles, C.S.J.***</i>	858
University of Ulm, Germany	
** California Institute of Technology, W.M. Keck Laboratory of Engineering Materials, Pasadena, USA	
*** Deutsche Bank AG, Corporates and Real Estate, Microtechnology Innovation Team, Berlin, Germany	
**** DeBeers Industrial Diamond Division (UK) Ltd., Charters, Sunninghill, Ascot, U.K.	
Performance of high speed diamond micro switch <i>Adamschik, M.; Schmid, P.; Ertl, S.*; Gluche, P.*; Flöter, A.*; Kohn, E.</i>	863
University of Ulm,	
* GFD, Ulm, Germany	
B-doping and piezoresistivity of CVD diamond <i>Johnston, C.*; Crossley, A.*; Chalker, P.R.**; Werner, M.***</i>	867
* AEA Technology plc, Harwell,	
** Liverpool University, U.K.	
*** Deutsche Bank AG, Berlin, Germany	
CVD diamond and its application in medical technologies <i>Gluche, P.*; Flöter, A.*; Ertl, S.*; Rösch, R.*; Lingenfelder, C.*; Adamschik, M.**; Dambacher, J.**; Kusterer, J.**; Kohn, E.**; Spraul, C.**; Lang, G.K.**; Thamasett, S.**; Hombach, V.**; Orth, K.**; Birke, J.**; Beger, H.**; Richter, H.P.**</i>	873
* GFD Gesellschaft für Diamantprodukte mbH, Ulm,	
** University of Ulm, Germany	
High-strain rate superplasticity due to Newtonian flow of supercooled liquid in bulk glassy alloys <i>Inoue, A.; Kawamura, Y.; Zhang, T.</i>	875
Tohoku University, Sendai, Japan	
Superhard and ultrasmooth carbon films for micromechanical components <i>Schultrich, B.; Scheibe, H.-J.; Siemroth, P.; Witke, T.</i>	876
Fraunhofer Institute IWS, Dresden, Germany	

Surface characterization of thermochemically polished CVD diamond films 880  
Weima, J.A.\*; Fahrner, W.R.\*; Zaitsev, A.M.\*\*; Blum, F.\*;  
Kosaca, G.C.\*  
\* University of Hagen,  
\*\* Ruhr University of Bochum, Germany

Determination of critical interfacial energy release rate in  
hard coatings on ductile substrate 884  
Jeong, J.-H.\*; Kim, J.-J.\*; Jeong, A.\*; Lee, K.-R.\*\*; Kwon, D.\*  
\* Seoul National University,  
\*\* Thin Film Technology Research Center, KIST, Seoul, South Korea

## ELECTRICAL AND ELECTRONIC PROPERTIES 889

Large area 4H-SiC power Schottky diode 890  
Rang, T.; Korolkov, O.; Pikkov, M.  
Tallinn Technical University, Estonia

Impact of a single grain boundary and the surrounding crystallites  
on the electronic properties of MOS-transistors 894  
Seifert, W.\*; Werner, M.\*\*

\* Fachhochschule Münster, Steinfurt,  
\*\* Deutsche Bank AG, CORE, Microtechnology Innovation Team,  
Berlin, Germany

Electrothermal interaction in power semiconductors 898  
Uhlenbrock, R.; Melbert, J.  
Ruhr-University Bochum, Germany

Electrical conductivity model of excimer laser treated polyimide 902  
Szilassi, Z.\*; Pászti, Z.\*\*; Hopp, B.\*\*\*; Chichak, S.\*\*\*\*; Ripka, G.\*;  
Mojzes, I.\*

\* Technical University of Budapest,  
\*\* Research Institute for Technical Physics and Materials Science of  
the Hungarian Academy of Sciences, Budapest,  
\*\*\* Research Group on Laser Physics of the Hungarian Academy of  
Sciences, Budapest, Hungary  
\*\*\*\* Uzhgorod State University, Uzhgorod, Ukraine

Anomalous trends in electronic properties of boron compounds BP, BAs, and BSb <i>Bouhafs, B.; Aourag, H.</i> <i>University of Sidi-Bel-Abbes, Algeria</i>	903
BaTiO <sub>3</sub> - ceramics cluster intergranular impedance model <i>Mitič, V.V.***; Petkovič, P.**; Mitrović, I.**</i> <i>* Serbian Academy of Sciences and Arts, Belgrade,</i> <i>** University of Niš, Yugoslavia</i>	904

<b>MICROSTRUCTURE AND MATERIAL PROPERTIES</b>	<b>909</b>
Stress and fatigue life modeling in thin attach layers <i>McCluskey, P.; Iyengar, R.; Parthasarathy, S.</i> <i>University of Maryland, USA</i>	910
Materials properties with respect to microsystem technologies <i>Mrosk, J.W.; Mahlich, M.; Kocdemir, B.; Fecht, H.-J.; Werner, M.*</i> <i>Ulm University,</i> <i>** Deutsche Bank AG, Microtechnology Innovation Team,</i> <i>Berlin, Germany</i>	911
Migration-resistant amorphous AlY metallizations for SAW devices <i>Berger, L.*; Mrosk, J.W.*; Ettl, C.*; Fecht, H.-J.*; Wolff, U.**</i> <i>* Ulm University,</i> <i>** Siemens AG, Corporate Technology, Munich, Germany</i>	915
Etching of microstructures and modification of solid surfaces by low energy ion beams <i>Lopour, F.*; Bábor, P.*; Šikola, T.*; Spousta, J.*; Dittrichová, L.*;</i> <i>Matějka, F.**; Duarte, J.C.C.***</i> <i>* Brno University of Technology,</i> <i>** Institute of Scientific Instruments, Czech Academy of Sciences,</i> <i>Brno, Czech Republic</i> <i>*** University of Minho, Braga, Portugal</i>	919

<b>MICROMATERIALS AND ENVIRONMENT</b>	<b>923</b>
Sensors and smart electronics in harsh environment applications <i>Fahrner, W.R.*; Job, R.*; Werner, M.**</i>	924
* University of Hagen,	
** Deutsche Bank AG, Innovationteam Microtechnology, Berlin, Germany	
Lead free alternatives: An analysis of performance characteristics <i>Huang, B.; Lee, N.-C.</i>	930
<i>Indium Corporation of America, Clinton, USA</i>	
Experiments for the assessment of biological effects of LCD material on the environment <i>Heinze, L.*; Kalnowski, G.**; Heppke, G.**</i>	941
* Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin,	
** Technical University Berlin, Germany	
Corrosion protection with conducting polymers: mechanism, stability and durability of the protective component <i>Lux, F.A.</i>	947
<i>Intelligent Polymer Research Institute, Wollongong University, Australia</i>	
Metal recycling as renewable resource of clean energy and raw materials <i>Kassem, M.E.</i>	949
<i>Assiut University, Egypt</i>	

<b>MATERIALS CHARACTERIZATION AND MICROMANUFACTURING</b>	<b>951</b>
Nano-scale machining of single-crystal silicon using a friction force microscope and identification of affected layer <i>Ashida, K.*; Chen, L.**; Morita, N.***; Yoshida, Y.***</i>	952
* Mechanical Engineering Laboratory, AIST, MITI, Tsukuba,	
** Graduate school of Chiba University,	
*** Chiba University, Japan	

<b>Micro-metalforming with silicon dies</b>	<b>956</b>
<i>Böhm, J.; Schubert, A.; Otto, T.*; Burkhardt, T.</i>	
<i>Fraunhofer Institute IWF, Chemnitz,</i>	
<i>* Fraunhofer Institute IZM, Chemnitz, Germany</i>	
<b>Porous silicon as new micro material for actuated 3D flip-up structures</b>	<b>960</b>
<i>Lammel, G.; Renaud, P.</i>	
<i>Swiss Federal Institute of Technology, Lausanne (EPFL), Switzerland</i>	
<b>Materials characterization on a nanometer scale at BESSY</b>	<b>964</b>
<i>Jung, C.; Weiss, M.R.; Gudat, W.</i>	
<i>BESSY mbH, Berlin, Germany</i>	
<b>Fritting contacts utilized for micromachined wafer probe cards</b>	<b>967</b>
<i>Kataoka, K.*; Itoh, T.*; Suga, T.*; Engelmann, G.**; Wolf, J.**;</i>	
<i>Ehrmann, O.**; Reichl, H.**</i>	
<i>* RCAST, University of Tokyo, Japan</i>	
<i>** Fraunhofer Institute IZM, Berlin, Germany</i>	
<b>MICROFABRICATION, MICROMACHINING, MICROMANUFACTURING</b>	<b>971</b>
<b>Ion implantation for micromaterial fabrication - fabrication and material properties</b>	<b>972</b>
<i>Nakano, S.*; Ogiso, H.***; Nakagawa, S.****; Ishikawa, H.*****;</i>	
<i>Sato, H.*</i>	
<i>* Mechanical Engineering Laboratory, AIST, MITI, Tsukuba,</i>	
<i>** National Institute for Advanced Interdisciplinary Research,</i>	
<i>AIST, MITI, Tsukuba,</i>	
<i>*** Okayama University of Science,</i>	
<i>**** University of Electro Communications, Tokyo, Japan</i>	
<b>Determination of heat treatment states fit for microcutting of steels</b>	<b>976</b>
<i>Peichl, A.; Hüntrup, V.; Schulze, V.; Spath, D.; Löhe, D.</i>	
<i>University of Karlsruhe (TH), Germany</i>	

<b>Superplastic microforming of amorphous alloy with microdies fabricated by UV-LIGA process</b>	980
<b>Saotome, Y.*; Kurosawa, Y.**; Kinuta, S.***; Inoue, A.****</b>	
* Gunma University, Kiryu,	
** Graduate school, Gunma University, Kiryu,	
*** Optonics precision Co. Ltd., Ashikaga,	
**** Tohoku University, Sendai, Japan	
<b>Microforging of ZrTiCuNiBe-bulk glass in the supercooled liquid state</b>	981
<b>Seidel, M.; Macht, M.-P.; Mechler, S.; Wanderka, N.</b>	
Hahn-Meitner-Institut Berlin, Germany	
<b>Superplastic extrusion of microgear shaft with photochemically machinable glass dies</b>	982
<b>Saotome, Y.*; Iwazaki, H.**</b>	
* Gunma University, Kiryu,	
** Graduate school, Gunma University, Kiryu, Japan	
<b>MECHATRONICS, ADAPTRONICS, MEMS</b>	983
<b>Micromechatronics - a foundation for future products</b>	984
<b>Kallenbach, E.; Schilling, C.; Frank, T.; Kallenbach, M.; Wurmus, H.</b>	
TU Ilmenau, Germany	
<b>Integration of micro-mechatronics in automotive applications</b>	986
<b>Ansorge, F.*; Becker, K.-F.**; Michel, B.*; Leutenbauer, R. *;</b>	
<b>Großer, V.*; Aschenbrenner, R.*; Reichl, H.*</b>	
* Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin,	
** Forschungsschwerpunkt Technologien der Mikroperipherik der TU Berlin, Germany	
<b>Advanced measurement techniques for microstructured surfaces</b>	987
<b>Fries, T.</b>	
FRT GmbH, Bergisch Gladbach, Germany	

<b>Modeling piezoelectric composites for adaptronics</b>	<b>993</b>
<i>Kreher, W.S.; Beckert, W.</i>	
<i>Technische Universität Dresden, Germany</i>	
<b>New equipment for evaluating performance of microelements on MEMS</b>	<b>997</b>
<i>Higo, Y.*; Takashima, K.*; Shimojo, M.*; Sugiura, S.**; Swain, M.V.***</i>	
<i>* Tokyo Institute of Technology,</i>	
<i>** Nissei Sangyo Co. Ltd., Tokyo, Japan</i>	
<i>*** The University of Sydney, Australia</i>	

## **SPECIAL APPLICATIONS** 1001

<b>Dicing of silicon wafers</b>	<b>1002</b>
<i>Inasaki, I.</i>	
<i>Keio University, Yokohama-shi, Japan</i>	
<b>Developing polymer based micromaterials using reclaimed micro-balloons</b>	<b>1018</b>
<i>Shukla, A.; Parameswaran, V.</i>	
<i>University of Rhode Island, Kingston, USA</i>	
<b>Development of a high-k composite for integral capacitors and the electrical property</b>	<b>1021</b>
<i>Ogitani, S.**; Silvestrov, V.*; Bidstrup-Allen, S.A.*; Kohl, P.*</i>	
<i>* Georgia Institute of Technology, Atlanta, USA</i>	
<i>** Asahi Chemical Industry Co., Ltd.</i>	
<b>Simulation of ferroelectric nonvolatile memory cells with MINIMOS-NT</b>	<b>1023</b>
<i>Dragosits, K.; Selberherr, S.</i>	
<i>TU Vienna, Austria</i>	
<b>Properties and integration study of oxazole dielectric OxD</b>	<b>1027</b>
<i>Sezi, R.*; Schmid, G.*; Engelhardt, M.*; Helneder, H.**;</i>	
<i>Schrenk, M.**; Schwerd, M.**; Seidel, U.**; Körner, H.**</i>	
<i>* Infineon Technologies AG, Erlangen,</i>	
<i>** Infineon Technologies AG, Munich, Germany</i>	

New perspectives of microtribology – methods and applications <i>Scherer, V.; Kullenberg, E.; Arnold, W.</i>	1031
<i>Fraunhofer Institute for Nondestructive Testing (IZFP), Saarbrücken, Germany</i>	
 Real-time monitoring and measurement of mechanical properties of polymeric films using resonant string structures <i>Kim, Y.-J.; Allen, M.G.*</i>	1035
<i>Samsung Electronic Co., Ltd., Korea</i>	
<i>* Georgia Institute of Technology, Atlanta, USA</i>	
 Preparation and modeling of fine-scaled 1-3 piezoelectric composites <i>Schönecker, A.*; Gebhardt, S.*; Seffner, L.*; Steinhausen, R.**; Hauke, T.**; Seifert, W.**; Beige, H.**</i>	1041
<i>* Fraunhofer-IKTS, Dresden, ** Martin-Luther-Universität Halle-Wittenberg, Germany</i>	
 The origin of the short stripe effect and creep controlled behavior in electromigration <i>Glickman, E.E.; Nathan, M.</i>	1042
<i>Tel Aviv University, Israel</i>	
 Experimental determination of the correlation between conductivity and mechanical stress of a silver-filled electrically conductive adhesive <i>Bornemann, J.; Schlimmer, M.</i>	1048
<i>Universität Gh Kassel, Germany</i>	
 Metal/polymer interfaces and composite materials prepared by vapor phase deposition <i>Behnke, K.; Strunskus, T.; Zaporojtchenko, V.; Faupel, F.</i>	1052
<i>University of Kiel, Germany</i>	
 Sol gel derived PZT thin films for MEMS applications <i>Maeda, R.; Wang, Z.; Chu, J.R.; Lin, W.M.</i>	1056
<i>Mechanical Engineering Laboratory, AIST/MITI, Tsukuba, Ibaraki, Japan</i>	

<b>Property profiles of materials for micro-structuring by hot-embossing</b>	1062
<b>Krabe, D.; Ebling, F.; Lang, G.; Arndt-Staufenbiel, N.</b>	
<i>Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin, Germany</i>	
<b>Modelling the cure-dependent viscoelastic behaviour of a thermosetting resin and residual curing stresses</b>	1063
<b>Kiasat, M.S.; Marissen, R.</b>	
<i>Delft University of Technology, The Netherlands</i>	
<b>Mechanical design support by means of FEA for advanced millimeter wave communication devices</b>	1067
<b>Sommer, J.-P.*; Michel, B.*; Döring, R.*; Hager, W.**; Rehme, F.**</b>	
* <i>Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin,</i>	
** <i>DaimlerChrysler Aerospace AG, Ulm, Germany</i>	
<b>Delay-time sensors for electrodiffusion measurements</b>	1071
<b>Bouabdallah, A.; Zizi, M.</b>	
<i>Institut de Physique, Bab Ezzouar, Alger</i>	
<b>Rapid prototyping of mesoscopic devices</b>	1073
<b>Stampfl, J.; Liu, H.-C.; Nam, S.W.; Kang, S.; Prinz, F.B.</b>	
<i>Stanford University, USA</i>	
<b>Thermographic testing methods with high temporal and spatial resolution</b>	1079
<b>Netzelmann, U.; Walle, G.; Karpen, W.; Meyendorf, N.</b>	
<i>Fraunhofer-Institute for Nondestructive Testing, Saarbruecken, Germany</i>	
<b>Application of new materials for integrated low-energy ignition elements in airbag systems - characterization and simulation</b>	1082
<b>Weiβ, U.*; Löbner, B.*; Gessner, T.*; Hoyer, W.*; Grambole, D.**</b>	
* <i>Chemnitz University of Technology,</i>	
** <i>FZ Rossendorf, Schönfeld-Weiβig, Germany</i>	
<b>Nanostructured shock-wave consolidated intermetallics</b>	1084
<b>Varin, R.A.*; Bystrzycki, J.**; Paszula, J.**; Song, Y.K.*</b>	
* <i>University of Waterloo, Canada</i>	
** <i>Military University of Technology, Poland</i>	

Characteristics of micro-metallic powders intended to be used in the production of electrochemical supplies current <i>Vasilescu, E.*; Vasilescu, I.**; Brenoaie, I.***</i>	1086
* University of Galati,	
** »Sidex« S.A Galati, Romania	
*** Metallurgical Surveyor to Lloyd's Register	
Control of electroplating depositions in MEMS-fabrication <i>Lütke Notarp, D.; Becker, M.; Benecke, W.</i> University of Bremen, Germany	1087
<b>6M TV TOWER WORKSHOP</b>	<b>1091</b>
Microelectronics and fiber-optics packaging: physical design for reliability <i>Suhir, E.</i> <i>Bell Laboratories, Lucent Technologies, Inc., Murray Hill, USA</i>	1092
Non-destructive characterization of magnetic layers and layer systems <i>Meyendorf, N.*/**; Altpeter, I.*; Netzelmann, U.*; Rösner, H.*/**;</i> <i>Hoffmann, J.**</i>	1094
* Fraunhofer-Institute for Nondestructive Testing, Saarbruecken, Germany	
** Center for Materials Diagnostics, UDRI, Dayton, USA	
Noncontacting laser based techniques for the determination of elastic constants of thin foils <i>Anwander, M.; Kaindl, G.; Klein, M.; Weiss, B.</i> University of Vienna, Austria	1100
Multi chip power packaging - reliability assessment <i>Hauck, T.; Paulasto, M.</i> Motorola AISL-Europe, Munich, Germany	1104

## **GERMAN RESEARCH PROGRAMS**

**1111**

Micromaterials topics in the German Materials Research Program MaTech 1112  
*Seitz, E.*

*Projectmanagement Organization New Materials and Chemical Technologies (NMT), Forschungszentrum Jülich GmbH, Germany*

Microproduction technology – key for micromaterials, innovative products, and new markets

**1116**

*Mikosch, F.; Scherr, S.*

*Forschungszentrum Karlsruhe GmbH, Germany*

Technologies and materials for micosystems

**1117**

*John, L.-G.*

*VDI/VDE Technologiezentrum Informationstechnik GmbH, Teltow, Germany*

The impact of research and market on the economic success of small and medium sized companies

**1120**

*Ilgner, J.; Köhler, T.; Mietke, S.; Werner, M.*

*Microtechnology Team of Deutsche Bank AG, Berlin, Germany*

## **POSTER SESSION**

**1123**

Influence of microstructure of electroless deposited Ni used as under bump metallization for high temperature soldering

**1124**

*Anhöck, S.\*; Ostmann, A.\*; Auerswald, E.\*\*; Nieland, C.\*; Reichl, H.\*\**

\* Technical University of Berlin, Center of Microperipheral, Berlin,

\*\* Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin, Germany

X-ray diffraction at elevated temperatures in the microsystem technology 1127

*Auerswald, E.\*; Anhöck, S.\*; Kieselstein, E.\*\*; Vogel, J.\*\*\**

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\*\* Chemnitzer Werkstoffmechanik GmbH, Chemnitz,

\*\*\* Angewandte Micro-Messtechnik, Rangsdorf, Germany

<b>Dy<sub>x</sub>O<sub>y</sub> film formation on the InP substrate</b>	1130
<i>Babushkina, N.V.; Malyshov, S.A.; Romanova, L.I.; Bykova, L.N.</i>	
<i>Institute of Electronics, National Academy of Sciences of Belarus, Minsk, Belarus</i>	
<b>Strength analysis of a micromechanical acceleration sensor by fracture mechanical approaches</b>	1133
<i>Bagdahn, J.*; Petzold, M.*; Seidel, H.**</i>	
<i>* Fraunhofer-Institut für Werkstoffmechanik, Halle, ** TEMIC TELEFUNKEN microelectronics GmbH, München, Germany</i>	
<b>Deformation and cracking at microindentations in GaAs</b>	1136
<i>Bergner, F.*; Bergmann, U.*; Schaper, M.*; Hammer, R.**; Jurisch, M.**</i>	
<i>* Dresden University of Technology, Dresden, ** Freiberger Compound Materials GmbH, Germany</i>	
<b>Elastic modules of solid C<sub>60</sub>:</b>	
<b>Measurement and relationship with nanostructure</b>	1139
<i>Blank, V.D.*; Prokhorov, V.M.*; Levin, V.M.**; Soifer, Ja.M.*; Kobelev, N.P.***</i>	
<i>* Technological Institute for Superhard and Novel Carbon Materials, Troitsk, ** Institute of Biochemical Physics, Moscow, *** Institute of Solid State Physics, Chernogolovka, Russia</i>	
<b>Reflective bistable liquid crystal displays on flexible substrates</b>	1140
<i>Boeffel, C.*; Bauer, M.*; Kuschel, F.**</i>	
<i>* Fraunhofer Institut für Zuverlässigkeit und Mikrointegration, Teltow, ** MLS GmbH, Leuna, Germany</i>	
<b>Dynamic Mechanical Analysis (DMA) of an highly-filled epoxy resin in thin layers</b>	1141
<i>Braun, T.*; Mießner, R.**; Becker, K.-F.*</i>	
<i>* Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin, ** Technische Universität Berlin, Microperipherals Center, Berlin, Germany</i>	

Thermotropic metal-containing liquid crystal polyurethanes,  
possessing the high electric conductivity

1144

Davletbaeva, I.M.\*; Ismagilova, A.I.\*; Davletbaev, R.S.\*;

Parfenov, V.V.\*\*

\* Kazan State Technological University,

\*\* Kazan State University, Russia

Humidity sorption in subnanometer-size local free volumes of  
polyimides: A positron lifetime study

1145

DLubek, G.\*; Buchhold, R.\*\*; Hübner, C.\*\*\*; Nakladal, A.\*\*;

Meyendorf, N.\*\*\*\*

\* ITA Institut für innovative Technologien GmbH, Köthen,

\*\* Technische Universität Dresden,

\*\*\* Martin-Luther-Universität Halle-Wittenberg,

\*\*\*\* IZFP Fraunhofer Institut Zerstörungsfreie Prüfverfahren,

Saarbrücken, Germany

Atomic scale structure changes during decomposition of Al alloys:

A positron annihilation study

1148

DLubek, G.\*\*; Depetasse, S.\*; Sourkov, A.\*; Meyendorf, N.\*;

Krause-Rehberg, R.\*\*\*

\* IZFP Fraunhofer Institut Zerstörungsfreie Prüfverfahren, Saarbrücken,

\*\* ITA Institut für innovative Technologien GmbH, Köthen,

\*\*\* Martin-Luther-Universität Halle-Wittenberg, Germany

Lead-free solders - rapidly reflowed under the laser beam

1151

Dorn, L.; Herbert, F.; Shrestha, S.

Technical University Berlin, Germany

In situ measurements of deformations on microelectronic  
components by microscopic methods

1153

Faust, W.; Bombach, C.; Michel, M.\*; Michel, B.

Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin,

\* Chemnitz University of Technology, Germany

Influence of different modeling approaches for solder and  
underfill on the reliability assessment of flip chip assemblies

1158

Feustel, F.; Wiese, S.; Meusel, E.

Dresden University of Technology, Germany

Rapid Prototyping of components and demonstrators  
in microsystem technology

1161

Vogel, J.\*; Döring, R.\*\*; Fleischer, L.\*\*\*; Faust, W.\*\*\*\*;  
Dost, M.\*\*; Michel, B.\*\*\*\*\*; Zeidler, H.\*\*\*\*\*

\* Angewandte Micro-Messtechnik GmbH, Rangsdorf,

\*\* Chemnitzer Werkstoffmechanik GmbH, Chemnitz,

\*\*\* GPA Dr. Fleischer und Partner GbR, Lichtenstein,

\*\*\*\* Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin,

\*\*\*\*\* NRU Präzisionstechnologie GmbH, Neukirchen/Chemnitz, Germany

The thermo-mechanical analysis of twin-chips silicon  
piezoresistive pressure sensors

1164

Friedel, K.; Wymyslowski, A.

Wroclaw University of Technology, Poland

Plastic reshaping of silicon microstructures: process,  
characterization and application

1165

Gärtner, E.; Frühauf, J.; Jänsch, E.

Technical University Chemnitz, Germany

Dielectric strength of ceramic substrates

1168

Gemeinert, M.; Güther, W.; Mücke, U.; Schiller, W.A.

Federal Institute for Materials Research and Testing,

Berlin, Germany

Analysis of structure and dimension of electronic parts with  
high resolution X-ray tomography

1170

Weidemann, G.\*; Habel, W.\*; Illerhaus, B.\*; Riesemeier, H.\*;

Goebbel, J.\*; Seifried, S.\*\*; Winterer, M.\*\*; Hahn, H.\*\*

\* Federal Institute of Materials Research and Testing (BAM), Berlin,

\*\* Darmstadt University of Technology, Germany

Strain measurement in solder interconnects of advanced  
electronics packages

1173

Gollhardt, A.; Vogel, D.; Michel, B.

Fraunhofer Institute for Reliability and Microintegration (IZM),

Berlin, Germany

Spectroscopic ellipsometry and dark conductivity measurements on p- and n-type microcrystalline silicon films <i>Grabosch, G.; Fahrner, W.R.</i> University of Hagen, Germany	1174
About the accuracy of the determination of mechanical properties of thin layers with the nanoindentation method <i>Herrmann, K.; Hasche, K.; Pohlenz, F.; Seemann, R.; Menelao, F.</i> Physikalisch-Technische Bundesanstalt Braunschweig und Berlin, Germany	1175
Automated optical measurements under vacuum <i>Hillmann, V.*/**; Großer, V.**; Gentzsch, S.****/****; Bloch, H.****;</i> <i>Michel, B.**</i> * Chemnitzer Werkstoffmechanik GmbH, ** Fraunhofer Institute IZM, Berlin, *** Angewandte Micro-Messtechnik GmbH, Rangsdorf, **** Aktiv Electronic GmbH, Berlin, Germany	1179
The micro stereoview strain analysis by the microscope Zeiss Neophot 21 with Praktica Scan 2000 <i>Horečka, L.; Berka, L.</i> Czech Technical University Prague, Czech Republic	1183
Patterning of thin plasma polymerized fluorcarbon films <i>Ianev, V.; Schwesinger, N.; Wurmus, H.</i> Ilmenau Technical University, Germany	1185
Combination of electroless and electroplating methods in electronics and instrument making <i>Khoperia, T.N.</i> Institute of Physics, Georgian Academy of Sciences, Tbilisi, Georgia	1189
Mechanical properties of micro-injection moulded components <i>Koch, T.; Seidler, S.</i> Vienna University of Technology, Austria	1192
Simulation of resonant interference of light by thin films <i>Kosobutskyy, Y.</i> State University »Lviv polytechnic«, Lviv, Ukraine	1195

- Surface modification due to technological treatment evaluated by SPM and XPS techniques 1201  
*Krause, F.\*; Halser, K.\*; Töpper, M.\*; Scherpinski, K.\*\**  
\* Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin,  
\*\* Technical University Berlin, Germany
- Synthesis, dielectrical and dynamic mechanical characterisation of new thermoplastic polyurethanes for pyro- and piezoelectric applications 1205  
*Krüger, H.\*; Frübing, P.\*\*; Gerhard-Multhaup, R.\*\**  
\* Fraunhofer Institute for Reliability and Microintegration (IZM),  
Branch Polymeric Materials and Composites, Teltow,  
\*\* University of Potsdam, Germany
- Temperature influence on current suppressing effect in SiC Schottky diode 1208  
*Kurel, R.; Rang, T.*  
Tallinn Technical University, Estonia
- Deformation behavior of micromirror arrays under optical power 1210  
*Kurth, S.\*; Kehr, K.\*; Faust, W.\*\*; Kaufmann, C.\*; Dötzel, W.\*;  
Gessner, T.\*; Michel, B.\*\**  
\* Chemnitz University of Technology,  
\*\* Fraunhofer Institute for Reliability and Microintegration (IZM),  
Berlin, Germany
- Lead-free solders for flipchip-technology 1213  
*Leonhard, W.\*; Gemmler, A.\*; Heck, W.\*\*; Jordan, M.\*\*\*;  
Gust, W.\*\*\*\**  
\* Fraunhofer-Institut für Produktionstechnik und  
Automatisierung (IPA), Stuttgart,  
\*\* Alcatel SEL AG, Stuttgart,  
\*\*\* Fa. Schlötter GmbH, Geislingen,  
\*\*\*\* Universität Stuttgart, Germany
- Development of micro scanning devices actuated with PZT thin films 1216  
*Lin, W.M.\*; Lee, C.\*\*; Schroth, A.\*\*\*; Matsumoto, S.; Maeda, R.*  
Mechanical Engineering Laboratory, AIST/MITI, Tsukuba, Japan  
\* Technology University of Dresden, Germany  
\*\* Metrodyne Microsystem Corp., Taiwan  
\*\*\* ISS-Nagano, Germany

The application of cluster intergranular impedance  
model for different BaTiO<sub>3</sub>-ceramics cluster structures

1219

Mitić, V.V.\*/\*\*; Petković, P.\*; Mitrović, I.\*

\* Serbian Academy of Sciences and Arts, Belgrade,

\*\* University of Niš, Yugoslavia

Synthesis and optical properties of diamond crystals

1222

Mudryi, A.V.\*; Shakin, I.A.\*; Solovyev, V.S.\*\*; Gusakov, G.A.\*\*

\* Institute of Physics of Solids and Semiconductors,

Academy of Sciences of Belarus, Minsk,

\*\* Belarussian State University, Minsk, Belarus

High aspect ratio structuring by ICP etching and metals and  
ceramics micro forming with powder injection molding

1223

Murakoshi, Y.; Shimizu, T.; Maeda, R.; Sano, T.

Mechanical Engineering Laboratory, AIST/MITI, Tsukuba,

Ibaraki, Japan

Humidity ceramic sensor materials on the basic of TiO<sub>2</sub>

1225

Nenov, T.

Technical University of Gabrovo, Bulgaria

Catalytic application of sol-gel deposited YSZ/Pd,Pt,RuO<sub>x</sub> and  
YSZ/Pd,Pt,Rh layers on Corning™ catalytic substrates

1228

Labus, S.; Oblakowski, J.; Gajerski, R.; Fuc, P.\*

University of Mining and Metallurgy, Kraków,

\* University of Technology, Poznan, Poland

Degradation of Pt electrodes and micro-heaters of NO<sub>x</sub> sensors

1231

Oblakowski, J.\*; Gajerski, R.\*; Labus, S.\*; Malecki, A.\*;

Prochowska-Klisch, B.\*; Fuc, P.\*\*

\* University of Mining and Metallurgy, Kraków,

\*\* University of Technology, Poznan, Poland

Measurement of the Young's modulus of ceramic substrates  
in the range of 20 – 300°C

1232

Rehmer, B.; Finn, M.; Gemeinert, M.; Schiller, W.A.

Federal Institute for Materials Research and Testing (BAM),  
Berlin, Germany

**Mode shape analysis of microstructures by means of  
laser-optical methods**

1234

*Rümmler, N.\*; Schnitzer, R.\*\*; Großer, V.\*\*\*; Michel, B.\*\*\**

\* AMITRONICS Angewandte Mikromechatronik GmbH, Seefeld,

\*\* Chemnitzer Werkstoffmechanik GmbH, Chemnitz,

\*\*\* Fraunhofer Institute for Reliability and Microintegration (IZM),  
Berlin, Germany

**Micro/nano formability of amorphous alloys in the supercooled  
liquid state**

1236

*Saotome, Y.\*; Inoue, A.\*\**

\* Gunma University, Kiryu,

\*\* Tohoku University, Sendai, Japan

**Development of in-situ nanoindentation system in a  
scanning electron microscopy**

1237

*Saotome, Y.\*; Yanagisawa, T.\*\**

\* Gunma University, Kiryu,

\*\* Graduate school, Gunma University, Kiryu, Japan

**Mechanical characterization of thin and ultrathin films by  
laser induced surface waves (Laser acoustics)**

1238

*Schneider, D.; Schwarz, T.; Witke, T.; Schultrich, B.*

*Fraunhofer-Institut für Werkstoff- und Strahltechnik,*

*Dresden, Germany*

**Glob Top-materials**

**Technical demands, properties, principles of material selection**

1239

*Schneider, W.*

*Microelectronic Packaging Dresden GmbH, Dresden, Germany*

**Researching of an ordered structure of porous anodic  
aluminum oxides**

1242

*Shulgov, W.*

*Belarusian State University of Informatics and Radioelectronics,  
Minsk, Belarus*

**Analysis of micromaterials**

1243

*Schwencke, B.; Müller, J.; Griese, H.*

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Berlin, Germany*

Characterisation of micro materials and micro components by combination of the micro-bending test and UNIDAC	1247
<i>Seiler, B.*; Kieselstein, E.*; Dost, M.*; Wielage, B.**; Michel, B.***</i>	
* Chemnitzer Werkstoffmechanik GmbH, Chemnitz,	
** Technical University of Chemnitz,	
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Micropillared layers based on porous alumina	1250
<i>Sokol, V.A.; Vorobyova, A.I.; Outkina, E.A.</i>	
Belarussian State University of Informatics and Radioelectronics, Minsk, Belarus	
Semi-additive and fully additive copper deposition on ORMOCER – a comparison	1252
<i>Stolle, T.*; Valizadeh, S.**; Lambert, D.***</i>	
* Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin, Germany	
** ACREO AB, Norrköping, Sweden	
*** Bull, VLSI Packaging, Les Clais-sous-Bois, France	
Near-field and far-field thermography in characterisation of microsystems	1257
<i>Szeloch, R.F.; Gotszalk, T.P.; Radojewski, J.; Janus, P.; Pedrak, R.; Orawski, W.</i>	
Wroclaw University of Technology, Poland	
Microstructure at indented thin GaN (0001) epilayers grown on 6H-SiC substrates	1260
<i>Trampert, A.*; Wagner, T.**; Thamm, A.*; Brandt, O.*; Ploog, K.H.*</i>	
* Paul-Drude-Institut für Festkörperforschung, Berlin,	
** Max-Planck-Institut für Metallforschung, Stuttgart, Germany	
Effect of inhomogeneity on the instrumented indentation test	1261
<i>Ullner, C.; Beckmann, J.</i>	
Federal Institute for Materials Research and Testing (BAM), Berlin, Germany	

- Experimental and numerical investigations of micro-electroplated sensors** 1264  
*Vogel, J.\*; Sommer, J.-P.\*\*; Noack, E.\*\*\*; Kieselstein, E.\*\*\*;  
Auerswald, E.\*\*; Gentzsch, S.\*\*\*\*; Großer, V.\*\*; Winkler, T.\*\*\*;  
Michel, B.\*\**  
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\*\*\* Chemnitzer Werkstoffmechanik GmbH, Chemnitz,  
\*\*\*\* now with: DLR e.V. Berlin, Germany
- Pillared microstructures of Al and Ta anodic oxides - advanced system for display technology** 1268  
*Vorobyova, A.I.; Outkina, E.A.*  
Belarussian State University of Informatics and Radioelectronics,  
Minsk, Belarus
- Evaluation of Glob Top Materials for Chip-on-Board (COB) applications** 1269  
*Walter, H.\*; Schneider, W.\*\*; Dudek, R.\*\*\*; Auerswald, E.\*\*\*;  
Schubert, A.\*\*\**  
\* AMIC , Angewandte Micro-Messtechnik GmbH, Rangsdorf,  
\*\* MPD Microelectronic Packaging Dresden GmbH,  
\*\*\* Fraunhofer Institute for Reliability and Microintegration (IZM),  
Berlin, Germany
- Tensile and fatigue testing for electronic materials with Microforce Testing System Tytron™ 250 (MTS)** 1272  
*Walter, H.\*; Schubert, A.\*\*; Priesnitz, U.\*\*\**  
\* AMIC, Angewandte Micro-Messtechnik GmbH, Rangsdorf,  
\*\* Fraunhofer Institute for Reliability and Microintegration (IZM), Berlin,  
\*\*\* MTS, Berlin, Germany
- Crack propagation in flip chip solder joints** 1273  
*Wiese, S.; Jakschik, S.; Feustel, F.; Heeg, J.; Meusel, E.  
Dresden University of Technology, Germany*

**Application of electroplating in MEMS-micromachining  
exemplified by a microrelay**

1276

*Becker, M.; Lütke Notarp, D.; Vogel, J.\*\*\*; Noack, E.\*\*; Großer, V.\*;  
Benecke, W.; Michel, B.\**

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*\*\*\* Angewandte Micro-Messtechnik GmbH, Rangsdorf, Germany*

**Investigation of bonding behaviour of different borosilicate glasses 1280**

*Wiemer, M.\*; Hiller, K.\*\*; Gessner, T.\*/\*\*; Kloss, T.\*\*\*;*

*Schneider, K.\*\*\*; Leipold-Haas, U.\*\*\*; Bagdahn, J.\*\*\*\*;*

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**Application of the zinc-silicat glass and GeO<sub>2</sub> thin films**

**as diffusion sources and encapsulants for GaAs and InP**

1283

*Shiolashvili, Z.\*; Jishiashvili, D.\*\*; Eterashvili, T.\*\*; Gobronidze, V.\*\**

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